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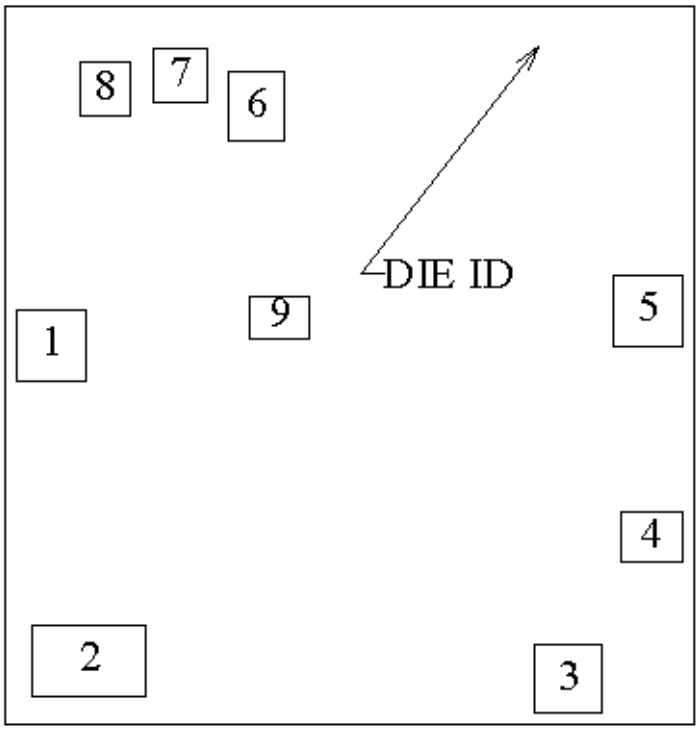
DPBU
Die Datasheet

LM135 MD8 MW8
PRECISION TEMPERATURE SENSORS

March 01,2004

DIE LAYOUT (B-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	135B	Bond Pad Opening Size (min)	112µm x 117µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100mm	Back Side Metal	Gold
Die Size (Drawn)	1194µm x 1143µm 47.0mils x 45.0mils	Back Side Connection	Floating or -VCC
Thickness	254µm Nominal		
Min Pitch	124µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
V+	1	-495	33	117	x	117
NC	2	-432	-491	188	x	119
V-	3	363	-521	112	x	117
NC	4	502	-284	104	x	81
ADJ	5	495	91	117	x	117
NC	6	-155	432	91	x	117
NC	7	-282	483	91	x	91
NC	8	-406	460	86	x	91
NC	9	-117	81	97	x	71

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